

Thick Film Chip Resistors, Alternate Terminations



MECHANICAL SPECIFICATIONS					
Resistive Element	Ruthenium oxide				
Encapsulation	Glass				
Substrate	96 % alumina				
Termination	Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available.				
Solder Finish	Base metallization without a solder finish standard. Hot solder dipped tin/silver or tin/lead/silver solder alloys available.				

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature: - 55 °C to + 150 °C

Moisture Resistance: Less than 0.5 % change when tested

per Method 106 of MIL-STD-202

Life: Less than 1 % change when tested per Method 108D

(+ 85 °C) of MIL-STD-202

Short Time Overload: Less than $0.5 \% \Delta R$

FEATURES

- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination: Gold, palladium silver, platinum gold, platinum silver or platinum palladium gold available

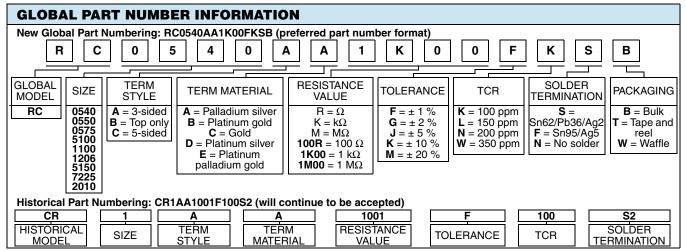


- Multiple styles, termination materials and configurations, allow wide design flexibility
- Non-magnetic terminations
- Flow solderable
- · Custom sizes available
- Burn-in data available
- · Automatic placement capability
- Available with either wraparound terminations or as a single termination flip chip
- Tape and reel packaging available
- Internationally standardized sizes
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition

STANDARD ELECTRICAL SPECIFICATIONS						
GLOBAL MODEL	POWER RATING P ₇₀ °C W	RESISTANCE RANGE ⁽¹⁾ Ω	TOLERANCE ± %	TEMPERATURE COEFFICIENT (2) (- 55 °C to + 150 °C) ± ppm/°C	MAXIMUM WORKING VOLTAGE ⁽³⁾ V	
RC0540	0.100	100 to 500k	1, 2, 5, 10, 20	100	40	
RC0550	0.100	100 to 500k	1, 2, 5, 10, 20	100	50	
RC0575	0.200	100 to 1M	1, 2, 5, 10, 20	100	70	
RC5100	0.250	100 to 1M	1, 2, 5, 10, 20	100	100	
RC1100	0.450	100 to 1M	1, 2, 5, 10, 20	100	100	
RC1206	0.300	100 to 1M	1, 2, 5, 10, 20	100	100	
RC5150	0.325	100 to 1M	1, 2, 5, 10, 20	100	125	
RC7225	0.525	100 to 1M	1, 2, 5, 10, 20	100	200	
RC2010	0.575	100 to 1M	1, 2, 5, 10, 20	100	200	

Notes

- (1) Higher values available. Please consult factory.
- $^{(2)}$ ± 100 ppm/°C standard thru 1 M Ω , ± 200 ppm/°C offered from 1.1 M Ω to 10 M Ω .
- (3) Continuous working voltage shall be $\sqrt{P \times R}$ or maximum working voltage, whichever is less.



Pb containing terminations are not RoHS compliant, exemptions may apply

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DIMENSIONS in inches (millimeters)						
Termination Style A (3-sided wraparound)	Termination Style B (Top conductor only)	Termination Style C (5-sided wraparound)	MODEL	LENGTH (L) ⁽⁴⁾ ± 0.006 (0.152)	WIDTH (W) ⁽⁴⁾ ± 0.006 (0.152)	THICKNESS (T) (4) ± 0.005 (0.127)
			RC0540	0.050 (1.27)	0.040 (1.02)	0.020 (0.508)
			RC0550	0.050 (1.27)	0.050 (1.27)	0.020 (0.508)
w ,	. / w /	/ W _	RC0575	0.075 (1.90)	0.050 (1.27)	0.020 (0.508)
	J/ //		RC5100	0.100 (2.54)	0.050 (1.27)	0.020 (0.508)
		Ţ //// ¬ ·	RC1100	0.100 (2.54)	0.100 (2.54)	0.020 (0.508)
0.025 [0.635] Max.	0.025 [0.635] Max.	0.025 [0.635] Max.	RC1206	0.125 (3.18)	0.062 (1.57)	0.025 (0.635)
	Wax.	,	RC5150	0.150 (3.81)	0.050 (1.27)	0.020 (0.508)
			RC7225	0.225 (5.72)	0.075 (1.90)	0.020 (0.508)
			RC2010	0.200 (5.08)	0.100 (2.54)	0.025 (0.635)

Note

⁽⁴⁾ All dimensions are before solder coating.

ТҮРЕ	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE/ MATERIAL CODE	SOLDER TERMINATION CODE	
Wire bondable/ Solderable	Platinum palladium gold	3-sided (wraparound)	AE		
		Top only (flip chip)	BE	N, F or S ⁽¹⁾	
		5-sided (wraparound)	CE		
Wire bondable/ Epoxy bondable	Gold	3-sided (wraparound)	AC		
		Top only (flip chip)	BC	N	
		5-sided (wraparound)	CC		
		3-sided (wraparound)	AA		
	Palladium silver (2)	Top only (flip chip)	BA		
Epoxy bondable		5-sided (wraparound)	CA		
		3-sided (wraparound)	AB		
	Platinum gold	Top only (flip chip)	BB	N	
		5-sided (wraparound)	СВ		
		3-sided (wraparound)	AD		
	Platinum silver	Top only (flip chip)	BD		
		5-sided (wraparound)	CD		

Notes

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⁽¹⁾ Use solder termination N for applications requiring wire bondable mounting, and solder terminations F or S for applications requiring solderable mounting

⁽²⁾ While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver



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